



# Process Qualification Report

## Reliability By Design

### Qualification Description:

The information contained herein represents proof of Reliability and Performance of the baseline process technology listed below in accordance with the Qualification Plan and test methods referenced in Section 8.0, after exposure to a variety of environments (electrical, thermal, humidity, etc) and mechanical events that may occur during installation and operational lifetime of the product. Upon conclusion of the testing the product continued to operate within specification limits, demonstrating its capability of reliable operation throughout its lifetime.

The purpose of this report is to present Qualification Test results of the of referenced process technology. The Pericom product data presented in this report qualifies all products manufactured using the exact semiconductor materials and processing techniques used in the baseline process and its off-shoot processes. The report describes the qualification test program, procedures used, criteria enforced (at the time of product validation), and the resulting test data obtained during the Qualification Test. The materials and processing techniques used in the baseline process are incorporated into the off-shoot processes, so the quality/integrity of the baseline and off-shoots (i.e.: 2PxM, 1PxM) processes will be equivalent.

### Lot Background Information:

Qual Test Date:	Jul-2008 updated Jul-12	By Ext. Process:	0.35um 1PxM
Process Technology:	0.35um 2P3M		0.35um 2PxM
Foundry & Code:	TSM7 (T)		
Qual Test Number:	WLR, QDT06002	Qual Part Number:	PI90SD1636

### Pericom's Qualification Test Results:

Stress Test	Test Procedure	Test Conditions	Duration	# of Lots	Samples per Lot	Results Pass/Fail
Dynamic High Temp	JESD22-A108	1000 hrs 3.6V 125°C	168 hrs	3	112	112 / 0
Operating Life		1000 hrs 3.6V 125°C	500 hrs	3	112	112 / 0
(DHTOL)		1000 hrs 3.6V 125°C	1000 hrs	3	112	112 / 0
	ELFR Rate is based on 336 units at 168 hours. FIT Rate is based on 336 units at 1,000 hours	<b>EFR Rate (40°C, 0.5 eV, 3.3V, 60% CL)</b>	<b>203.8</b>			
		<b>FIT Rate (40°C, 0.5 eV, 3.3V, 60% CL)</b>	<b>34.2</b>			
		<b>Calculated MTBF</b>	<b>29,200,971</b>			
Temp Cycle Test	JESD22-A104	-65°C to 150°C, 500 cycles	100 cycles	3	25	25 / 0
		-65°C to 150°C, 500 cycles	500 cycles	3	25	25 / 0
High Temp Storage	JESD22-A103	1000hrs, 0V, 150°C	168 hrs	3	15	15 / 0
(HTS)		1000hrs, 0V, 150°C	500 hrs	3	15	15 / 0
		1000hrs, 0V, 150°C	1000 hrs	3	15	15 / 0
Latch Up Test	EIA JESD78	Report available by Device				
ESD-HBM Test	JESD22-A114	Report available by Device				

### Qualification by Extension Information:

It is valid to use the reliability data of a particular process technology and apply to all products within this process technology family. All parts within the same family are designed to the same rules (layout & electrical), and manufacturing is controlled by SPC. Within a product family, a device can only be fabricated on one process technology option.

If there are any questions about this qualification, please contact Quality Support at: [customerquestion@pericom.com](mailto:customerquestion@pericom.com)